

**REMARKS**

In the official Office Action dated July 23, 2001 in the above-captioned application, the Examiner required a restriction under 35 U.S.C. § 121 to one of the following inventions:

- I. Claims 25-31 and 40-47, drawn to a semiconductor device and die-bonding material; or
- II. Claims 32-39, drawn to a method of making a semiconductor device.

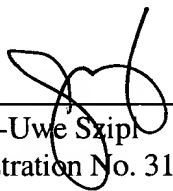
The Examiner justifies the requirement because claim 46 refers to a metal filler which is not referred to in method claims 32-39. However, by this amendment, applicants add new claim 48, a process dependant on claim 39, wherein the filmy die-bonding material comprises a metal filler.

In view of the above, the requirement is believed to be moot in that the only justification for the requirement has been obviated. However, should the requirement be improperly maintained, the applicants elect with traverse the invention of group I, i.e., claims 25-31 and 40-47 drawn to a semiconductor device and die-bonding material. Applicants specifically reserve the right to file a divisional application to the non-elected subject matter.

Accordingly, it is believed that this application is now in condition for examination, and the Examiner's early and favorable consideration is earnestly solicited. Questions are welcomed by the below-signed attorney for applicants.

Respectfully submitted,

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